

INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

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Sheet 1 of 5 A4

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## Complete if Known

Application Number	10/601,938
Filing Date	June 23, 2003
First Named Inventor	Krishna K. Nair
Group Art Unit	2829
Examiner Name	Douglas M. Menz
Attorney Docket Number	9180-29

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		Number	Kind Code (if known)		
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Examiner Signature

*Douglas Menz*

Date Considered

6/7/05

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE  
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## Complete If Known

Application Number	10/601,938
Filing Date	June 23, 2003
First Named Inventor	Krishna K. Nair
Group Art Unit	2829
Examiner Name	Douglas M. Menz

Attorney Docket Number

9180-29

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Examiner Signature

Date Considered

6/7/05

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<p>Substitute form 1449A/PTO</p> <p><b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b></p> <p>(use as many sheets as necessary)</p>				<b>Complete if Known</b>	
				Application Number	10/601,938
				Filing Date	June 23, 2003
				First Named Inventor	Krishna K. Nair
				Group Art Unit	2829
				Examiner Name	Douglas M. Menz
Sheet	3	of 5	A4	Attorney Docket Number	9180-29

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Examiner Signature	<i>Douglas M. Menz</i>	Date Considered	6/17/05
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Substitute form 1449A/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)				<b>Complete if Known</b>	
Sheet	4	of 5	A4	Application Number	10/601,938
				Filing Date	June 23, 2003
				First Named Inventor	Krishna K. Nair
				Group Art Unit	2829
				Examiner Name	Douglas M. Menz
				Attorney Docket Number	9180-29

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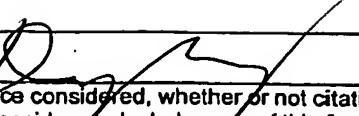
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
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Examiner Signature		Date Considered	6/8/05
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				Examiner Name	Douglas M. Menz
Sheet	5	of 5	A4	Attorney Docket Number	9180-29

*DK*   Electronics Packaging Conference, Austin, Texas, pp 14-25 (Sep. 29-Oct. 1, 1996).  

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